

Notice of References Cited	Application/Control No. 10/765,917	Applicant(s)/Patent Under Reexamination WADA ET AL.	
	Examiner Paul D. Kim	Art Unit 3729	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,759,258	07-2004	Kasukabe et al.	438/17
*	B	US-6,696,849	02-2004	Ban et al.	324/760
*	C	US-3,605,230	09-1971		492/53
*	D	US-6,147,505	11-2000	Ott et al.	324/754
*	E	US-5,945,834	08-1999	Nakata et al.	324/754
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Microrelay packaging technology using flip-chip assembly"; Miller, D.C.; Wenge Zhang; Bright, V.M.; Micro Electro Mechanical Systems, 2000. MEMS 2000. The Thirteenth Annual International Conference on 23-27 Jan. 2000; Pages:265 - 270.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.